

Welcome to **E-XFL.COM**

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	128
Number of Gates	-
Voltage - Supply	3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 90°C (TJ)
Package / Case	208-BGA
Supplier Device Package	208-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lx128v-5f208c

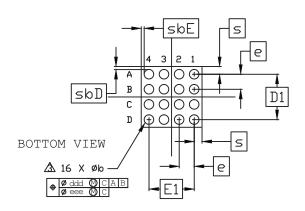
Email: info@E-XFL.COM

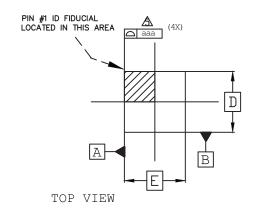
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

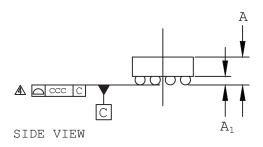


16-Ball WLCS Package Option 2: iCE40 UltraLite™

Dimensions in Millimeters







NOTES:

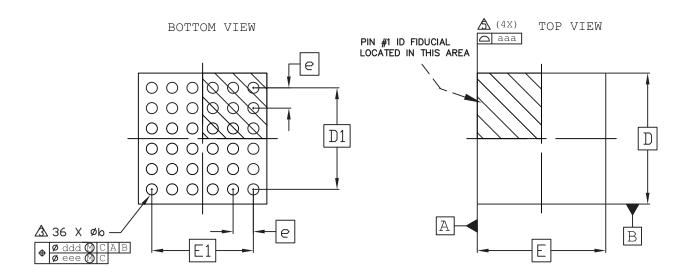
- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- \triangle PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- $\underline{\mathbb{A}}$ BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

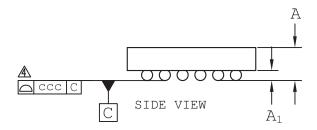
REF.	Min.	Nom.	Max.
Α	0.413	0.452	0.491
A1	0.122	0.152	0.182
b	0.188	0.218	0.248
D	1.	409 BS	С
Ε	1.	409 BS	С
D1		1.05 BSC)
E1		1.05 BSC)
е	(0.35 BS0)
S	-	0.180	-
sbD	0.067	0.071	0.072
sbE	0.067	0.071	0.072
ممم	0.03		
CCC	0.03		
ddd	0.050		
eee		0.015	



36-Ball WLCS Package Option 3: LIFMD™

Dimensions in Millimeters





NOTES:

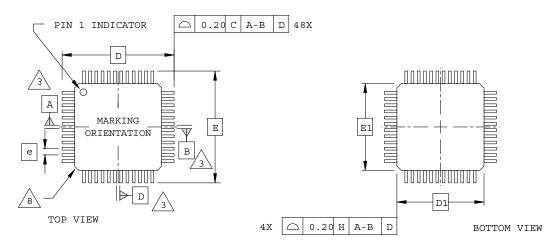
- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- \triangle PRIMARY DATUM $\boxed{\text{C}}$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- \triangle BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

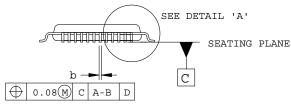
REF.	Min.	Nom.	Max.
А	-	-	0.600
A1	0.113	-	-
b	0.188	0.218	0.248
D	:	2.535 BS	С
E		2.583 BS	С
D1	2.00 BSC		
E1	2.00 BSC		
е	0.40 BSC		
aaa	0.030		
ccc	0.050		
ddd		0.050	
eee		0.015	

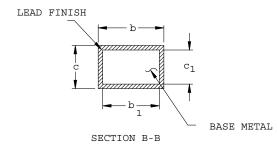


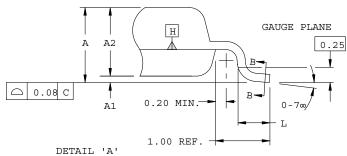
48-Pin TQFP Package (1.0 mm thick)

Dimensions in Millimeters









NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\stackrel{\textstyle }{\searrow}$ datums a, b and d to be determined at datum plane H.

- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

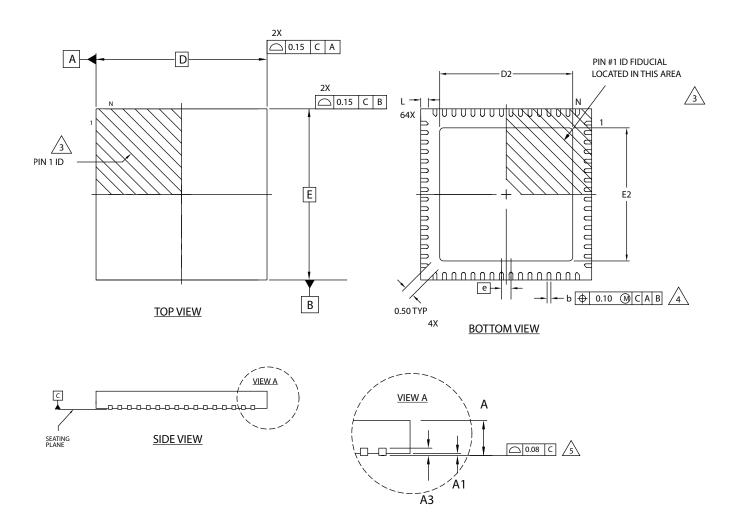
8 EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.20
A1	0.05	-	0.15
A2	. 95	1.00	1.05
D	9.00 BSC		
D1	7.00 BSC		
Е		9.00 BSC	
E1	7.00 BSC		
L	0.45	0.60	0.75
N		48	
е		0.50 BSC	
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
С	0.09	0.15	0.20
c1	0.09	0.13	0.16



64-Pin QFNS Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

DIMENSION b APPLIES TO PLATED
TERMINAL AND IS MEASURED BETWEEN
0.15 AND 0.30 mm FROM TERMINAL TIP.

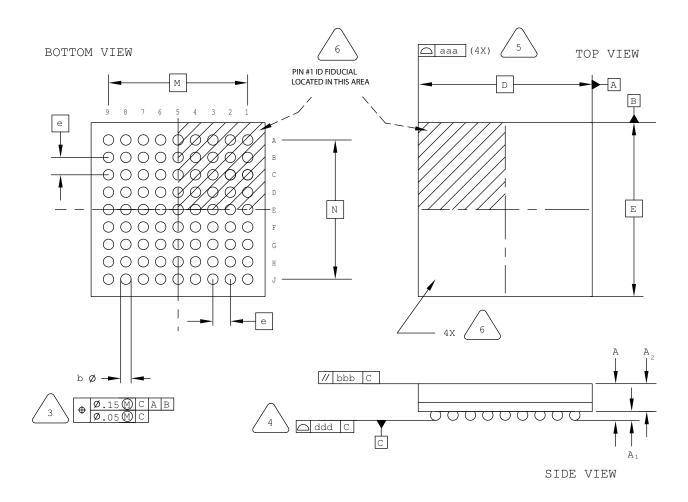
__________________________________APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
А3	0.2 REF		
D	9.0 BSC		
D2	5.00	_	7.50
E	9.0 BSC		
E2	5.00	-	7.50
b	0.18	0.24	0.30
е	0.50 BSC		
L	0.30	0.40	0.50



81-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

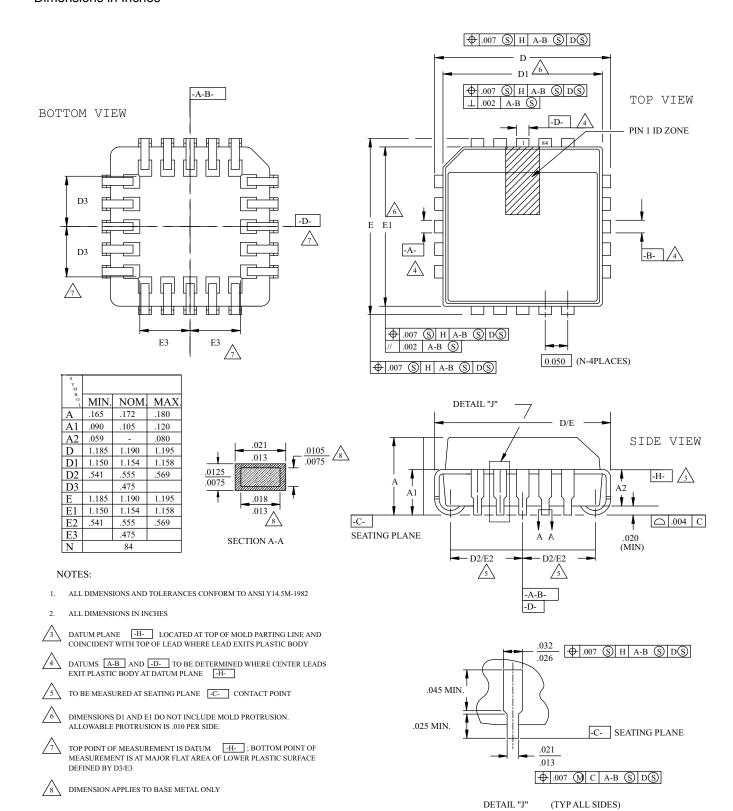


SYMBOL	MIN.	NOM.	MAX.
А	-	ı	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	5	5.00 BSC	
M/N	4.00 BSC		
b	0.20	0.25	0.30
е	O	.50 BSC	
aaa	-	_	0.10
bbb	-	_	0.10
ddd	_	_	0.10



84-Pin PLCC Package

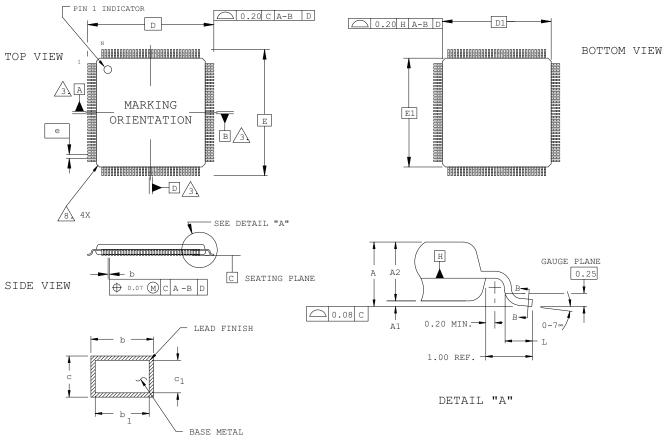
Dimensions in Inches





128-Pin TQFP Package

Dimensions in Millimeters



SECTION B - B

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\sqrt{3}$ DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
 ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

8 EXACT SHAPE OF EACH CORNER IS OPTIONAL.

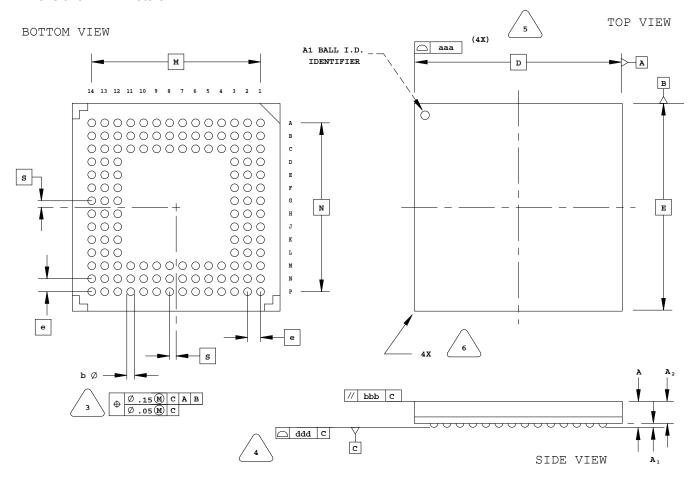
SIDE VIEW

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	16.00 BSC		
D1		14.00 BSC	
Е		16.00 BSC	
E1		14.00 BSC	
L	0.45	0.60	0.75
N		128	
е		0.40 BSC	
b	0.13 0.18 0.		0.23
b1	0.13	0.16	0.19
С	0.09	0.15	0.20
c1	0.09	0.13	0.16



132-Ball csBGA Package Option 1: MachXO2, MachXO, LatticeXP2™

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

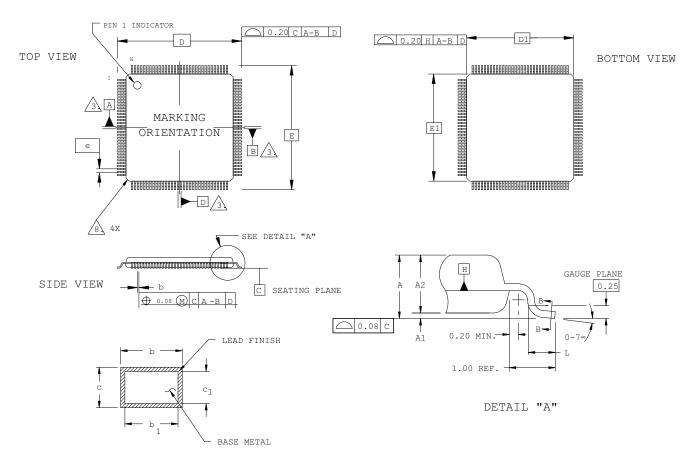


	Г		
SYMBOL	MIN.	NOM.	MAX.
A	0.90	1.23	1.35
A1	0.15	-	-
A2	-	-	1.10
D/E	8	.00 BSC	
M/N	6.50 BSC		
s	0.	.25 BSC	
b	0.25	0.30	0.35
е	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08



144-Pin TQFP Package

Dimensions in Millimeters



SECTION B - B

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\sqrt{}_3$ DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 7. Al is defined as the distance from the seating plane to the lowest point on the package body.

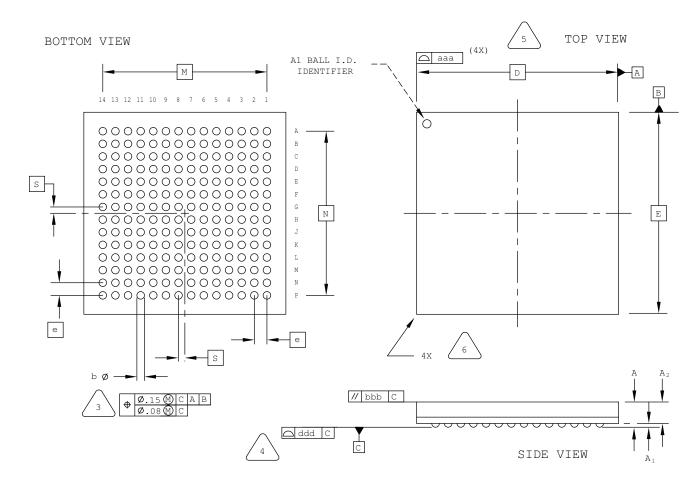
 $\sqrt{8}$ EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	22.00 BSC		
D1	20.00 BSC		
Е		22.00 BSC	
E1		20.00 BSC	
L	0.45	0.60	0.75
N		144	
е		0.50 BSC	
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
С	0.09	0.15	0.20
c1	0.09	0.13	0.16



196-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

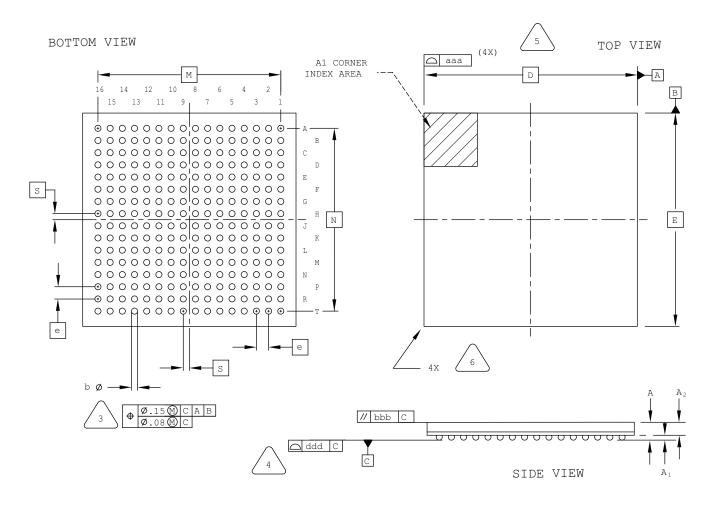


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.15	_	_
A2	_	_	0.85
D/E	8	.00 BSC	
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
е	0.50 BSC		
aaa	_	_	0.10
bbb	_	_	0.10
ddd	_	_	0.08



256-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

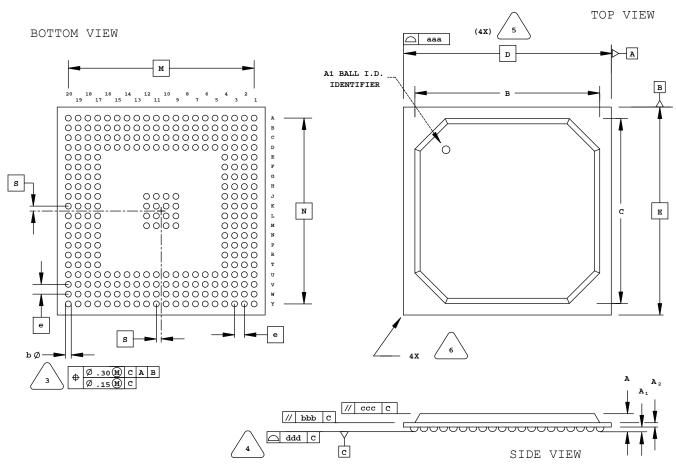
7. REFERENCE JEDEC MO-275, VARIATION JJAB-2.

SYMBOL	MIN.	NOM.	MAX.
А	_	-	1.70
A1	0.25	1	_
A2	0.65	ı	-
D/E	14.0 BSC		
M/N	12.0 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
е	0.80 BSC		
aaa	_	_	0.15
bbb	_	_	0.20
ddd	_	_	0.20



272-Ball BGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

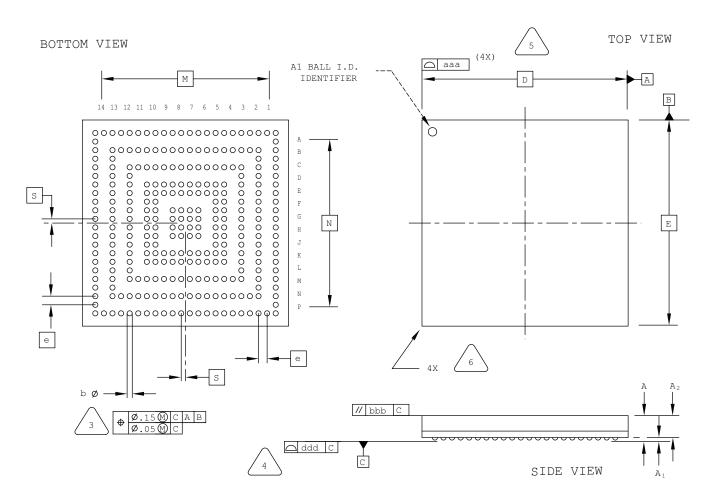


SYMBOL	MIN.	NOM.	MAX.	
A	1.90	2.25	2.80	
A1	0.50	0.65	0.80	
A2	0.28	0.54	0.80	
B/C	23.80	24.30	24.80	
D/E	2	7.00 BSC		
M/N	24	24.13 BSC		
s	0	0.635 BSC		
b	0.60	0.75	0.90	
е	1.27 BSC			
aaa	-	-	0.20	
bbb			0.25	
ccc	-	-	0.35	
ddd	-	-	0.20	



284-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

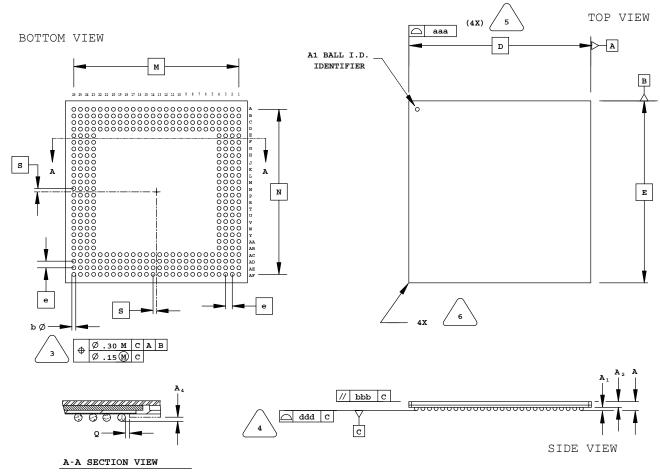


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.15	_	ı
A2	_	-	0.85
D/E	12.00 BSC		
M/N	10.50 BSC		
S	0.25 BSC		
b	0.25	0.31	0.37
е	0.50 BSC		
aaa	_	_	0.10
bbb	_	_	0.10
ddd	_	_	0.08



352-Ball SBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

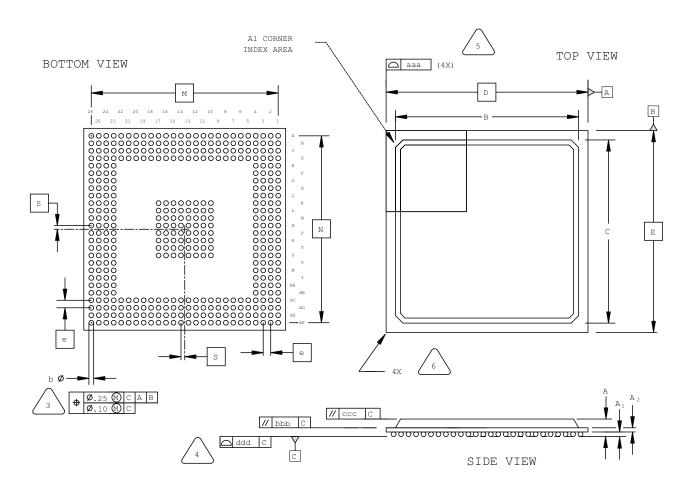


SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.50	0.65	0.80
A2	0.80	0.90	1.00
D/E	35	5.00 BSC	
M/N	31.75 BSC		
s	0.635 BSC		
b	0.60	0.75	0.90
е	1.27 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20



416-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

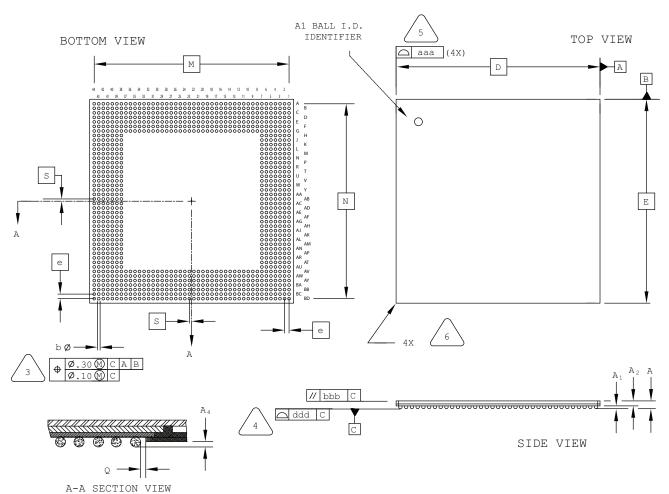


SYMBOL	MIN.	NOM.	MAX.
А	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	23.80	24.80	25.80
D/E	27.00 BSC		
M/N	25.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	_	0.25
ccc	-	_	0.35
ddd	_	_	0.20



1036-Ball ftSBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

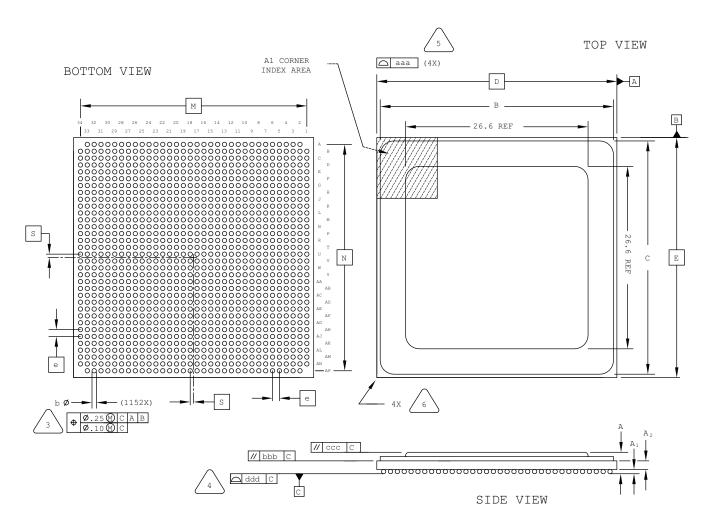


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.80
A1	0.40	0.55	0.70
A2	0.90	0.98	1.10
D/E	4.	5.00 BSC	
M/N	43.00 BSC		
S	0.50 BSC		
b	0.50	0.65	0.80
е	1.00 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.35
ddd	-	-	0.20



1152-Ball Organic fcBGA Package Option 1: LatticeSC/SCM40

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

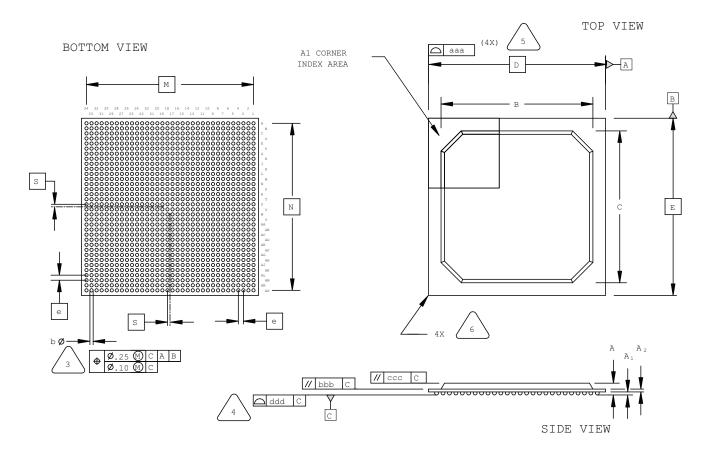


SYMBOL	MIN.	NOM.	MAX.
A	2.55	2.90	3.25
A1	0.35	0.50	0.65
A2	1	.20 REF	
B/C	34.25	34.50	34.75
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	_	_	0.20



1156-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

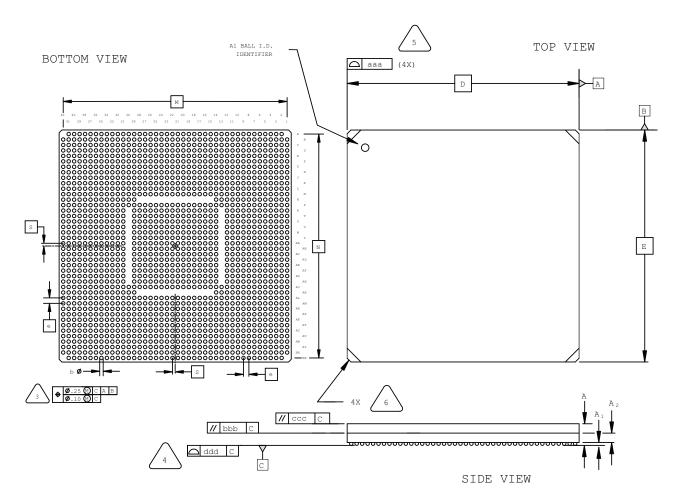


SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.25	2.60
A1	0.30	0.50	0.70
A2	0.40	0.60	0.80
B/C	29.80	30.30	30.80
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	_	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20



1704-Ball Ceramic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY. PACKAGE BODY INCLUDES SUBSTRATE AND LID.





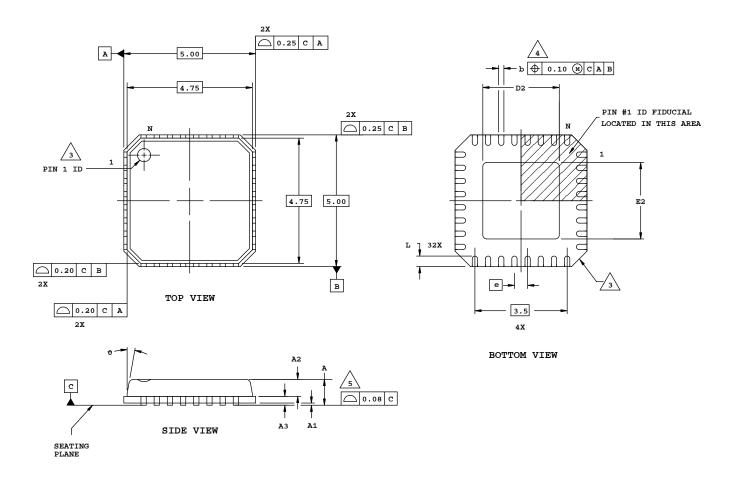
SYMBOL	MIN.	NOM.	MAX.
A	4.30	4.80	5.30
A1	0.30	0.50	0.70
A2	1.30	1.60	1.90
D/E	42.50 BSC		
M/N	41.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa			0.20
bbb			0.25
ccc	-	-	0.35
ddd	-	-	0.20



Appendix A. Package Archive

32-Pin QFN (Punch Singulated) Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

<u>3</u> I

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.



DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 mm FROM TERMINAL TIP.



APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	-	0.85	1.00
A1	0.00	0.01	0.05
A2	0.00	0.65	1.00
A 3	0.20 REF		
D2	1.25	2.70	3.25
E2	1.25	2.70	3.25
е	0.50 BSC		
b	0.18	0.24	0.30
L	0.30	0.40	0.50
Ð	-	-	12